SMT3/SMTE3

Surface Mount Tactile Switches





■ Features -

- 1. Compatible With Lead-Free, Reflow Soldering Heat-resistance resin for lead-free soldering.
- 2. Washable (SMTE3 Series)
- 3. J-Lead Terminal Pins For High-Density Mounting
- 4. Anti-Static Electricity (SMTE3 Series) Ground terminal is provided to prevent damage to element caused by static electricity.

■ Specifications -

	Max.	0.6 VA max. (24 VDC max. 30 mA max.) (Resistive load)	
Rating	Min.	Silver plated contacts	1 mA 5 VDC(Resistive load)
		Gold plated contacts	10 μA 5 VDC(Resistive load)
Initial contact resistance		100mΩ max.	(1.5mA 200µVAC)
Dielectric strength		250VAC 1 minute	
Insulation resistance		100MΩ min. $(100VDC)$	
Electrostatic capacity		5pF max.	
Electrical life		100,000 operations	
Stroke	SMT3	0.25mm	
	SMTE3	0.5mm	
Operating force	SMT3	1.18±0.39 N	
	SMTE3	1.96±0.98 N	
Operating temperature range		-25∼+70°C	
Storage temperature range		-40∼+85°C	

■ Structure -

■ Part Numbering

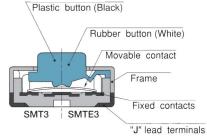
SMT E G 3 - 01 E - 2

Series code Structure Contact plating Series No. Registration No. Packaging specs.

	l l	
None	Standard type	
	(Plastic button)	
Е	Immersion washable (Rubber button)	

None	Silver plated
G	Gold plated





■ Table of Part Numbers

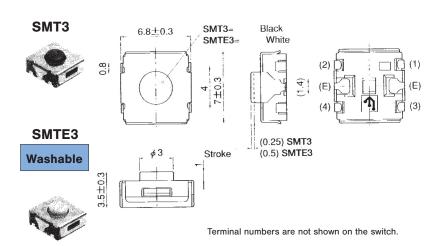
Structure	Packaging specifications		
Structure	Stick	Emboss taping	
Standard type	SMT3-01-Z	SMT3-01E-Z ★ SMTG3-01E-Z	
Immersion washable	SMTE3-01-Z ★ SMTEG3-01-Z	SMTE3-01E-Z ★ SMTEG3-01E-Z	

■Pad Layouts

(Top view)

Ground terminals	Without	With
Part No.	SMT3 • SMTE3 SMTG3 • SMTEG3	SMTE3 SMTEG3
Pattern dimensions	3.2 3.6 3.2	3.2 3.6 3.2 - (1) (2) - (E) (E) (E) (4)

SPST



	Switchng function	
Part No.		Push
SMT3-01-Z SMT3-01E-Z SMTG3-01E-Z SMTE3-01-Z SMTE3-01E-Z SMTEG3-01-Z SMTEG3-01E-Z	OFF	(ON)
Connecting terminals		1 - 3
Circuit diagrams	(1) O (2) (3) O (4)	
	(E) (E)	

(ON): Momentary

(E) : Ground terminal (SMTE3 and SMTEG3 series)

■Soldering Specifications

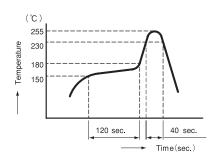
(1) Manual Soldering

Device: Soldering iron

 1350° C ± 10° C; 3 ± 0.5 seconds

(2) Reflow Soldering

Device: Inline or batch system



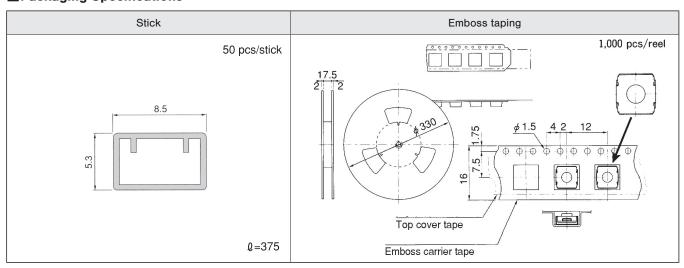
Apply reflow soldering up to 2 times max.

■Flux Cleaning

Since the **SMT3** series is not process sealed, be sure to use low-residue flux.

- (1) Solvent: Fluorine or Alcohol type Cleaning with other solvents or water is not possible.
- (2) Cleaning after soldering should be done after the terminal temperature falls to 90°C or below, or after leaving the switch for five minutes or longer at room temperature. Cleaning temperature: 43°C, max.
- (3) Do not use ultrasonic cleaning.

■ Packaging Specifications



When ordering, tape packaged version shall be supplied by request. Minimum packaging quantity for reel packaging is 1,000pcs per reel.